

# DDR3 Code Information

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## Component

## Part Number Decoder

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# Part Number Decoder

**K** **4** **B** X X X X X X X - X X X X X X

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 1. Memory (K)

## 2. DRAM : 4

## 3. Small Classification

B : DDR3 SDRAM

## 4~5. Density

51 : 512Mb

1G : 1G

2G : 2G

4G : 4G

## 6~7. Bit Organization

04 : x4

08 : x8

16 : x16

## 8. # of Internal Banks

3 : 4 Banks

4 : 8 Banks

5 : 16 Banks

## 9. Interface, VDD, VDDQ

6 : SSTL, 1.5V, 1.5V

## 10. Generation

M : M-die

A : A-die

B : B-die

C : C-die

D : D-die

E : E-die

F : F-die

G : G-die

H : H-die

## 11. "-"

## 12. Package

Z : FBGA (Lead-Free)

H : FBGA (Lead-Free & Halogen-Free)

J : FBGA (Lead-Free, DDP)

M : FBGA (Lead-Free & Halogen-Free, DDP)

B : FBGA (Lead-Free & Halogen-Free, Flip Chip)

## 13. Temp, Power

C : Commercial Temp.(0°C ~ 85°C), Normal Power

Y : Commercial Temp.(0°C ~ 85°C), Low VDD(1.35V)

## 14~15. Speed (Wafer/Chip Biz/BGD: 00)

F7 : DDR3-800 (400Mhz@CL=6, tRCD=6, tRP=6)

F8 : DDR3-1066 (533MHz@CL=7, tRCD=7, tRP=7)

H9 : DDR3-1333 (667MHz@CL=9, tRCD=9, tRP=9)

K0 : DDR3-1600 (800MHz@CL=11, tRCD=11, tRP=11)

MA : DDR3-1866 (933MHz@CL=13, tRCD=13, tRP=13)

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## 16. Packing "Packing Type Reference"

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other ( Tray, Tube, Jar )	0 ( Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

## 17~18. Customer "Customer List Reference"